

## **Electronics News Submission Guidelines**

*Electronics News* invites editorial contributions that provide technical information about equipment, technology, methods and services written for electronics designers, manufacturing managers, engineers, scientists, electronics technical managers, contract manufacturers, operations/production managers and educational providers.

### **Types of articles**

Articles for publication in *Electronics News* may be original research reports; product reviews; or discussions of new products, equipment, technology, regulations, and educational developments. They may also be opinions or commentaries on current events that affect the electronics industry.

Serial articles are not accepted for publication; each article must be complete.

Writers are encouraged to submit via e-mail either a completed article or an outline of a proposed article to [Catherine Pickavet](#), *Electronics News* editor.

### **Criteria for acceptance**

To be considered for publication, an article must report on a significant development; have a direct bearing on electronics; include sufficient data to support claims and/or conclusions; and not be under consideration for publication elsewhere.

Other reasons besides quality, however, affect the decision to accept or reject an article. Among these are the amount of space available, the quality of other articles competing for that space, the mix of articles desired, and the expected degree of interest to *Electronics News* readers.

For these reasons, an article that otherwise meets the criteria enumerated above may occasionally be rejected.

### **Copyright**

Feature articles accepted for publication become the sole property of the publisher, *Electronics News*, which holds the copyright. Copyright laws prohibit reproduction by anyone, including authors, without permission. Requests for permission to reproduce material should be made by writing to the editor.

### **Editing**

Once editorial is accepted, it is edited to make sure that grammar and punctuation are correct, ideas are expressed clearly, no ambiguities exist, and the editorial is in the *Electronics News* style.

### **Style**

Write the article in a feature style, not the standard scientific report style (See *Electronics News* for examples).

Divide the article into sections and suggest headings ("subheads") that briefly describe the contents of each section.

### **Images**

Email images as JPGs that are 300dpi at about postcard size, or 118 pixels/cm at about 10cm x 15cm.

### **Captions**

Write captions that are self-explanatory without reference to the text.

### **Issues of interest:**

Developments in electronics practices and techniques; insight and comments about trends and developments; new technology; environmentally friendly measures and projects; commentary about critical issues affecting the industry (i.e. government regulation, skills shortages, sustainable development, safety and health, etc.), and interesting new products and outstanding achievements. For more information, contact Catherine Pickavet on (02) 9422 2862, or email [catherine.pickavet@reedbusiness.com.au](mailto:catherine.pickavet@reedbusiness.com.au).

**Topics of interest:**

AC-DC/DC-DC converters

Actuators

Analogue ICs

ASICs

Automotive electronics

Avionics military electronics

Batteries

Capacitors/resistors

Circuit design

Computer and peripherals

Connectivity

Connectors and interconnection

Consumer electronics

Contract manufacturing

Crystals

Data acquisition

Design tools

Development kits

Digital ICs

Digital power

Displays

Education and training

EM/EMC filters and filtering

Embedded computing

Enclosures

Ethernet

FPGAs

LEDs

Medical electronics

Memory chips/modules

Memory developments

Microcontrollers

Microprocessors

Microwave RF components

Motion control

Motors

Nanotechnology

Offshoring

Optoelectronics

Oscillators

PCB assembly

Power management

Power supplies

Programmable logic

Security electronics

Sensors

Solar energy systems

Soldering

Solid state switches  
Test and measurement  
Thermal management  
Transistors  
Wafer fabrication  
Wireless